

LNJ121W84RA

Surface Mounting Chip LED

Dome-Lens 2 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

• Yellow Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	60	mW
Forward current	I_F	20	mA
Pulse forward current	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

• Yellow Green

• Red

• Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

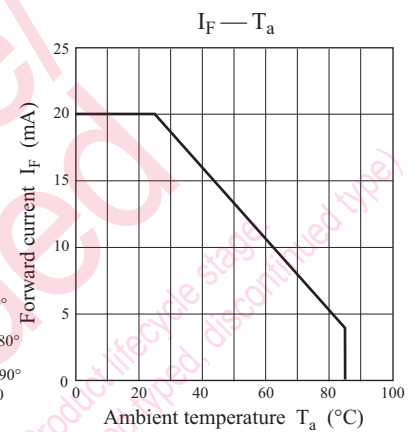
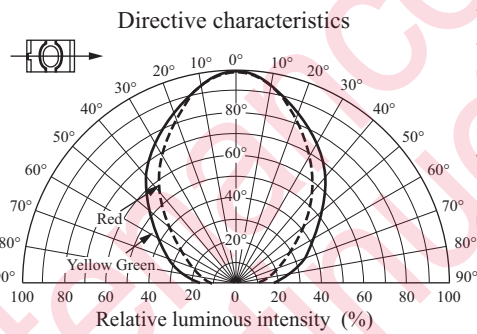
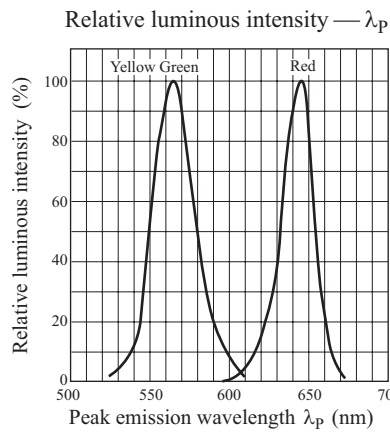
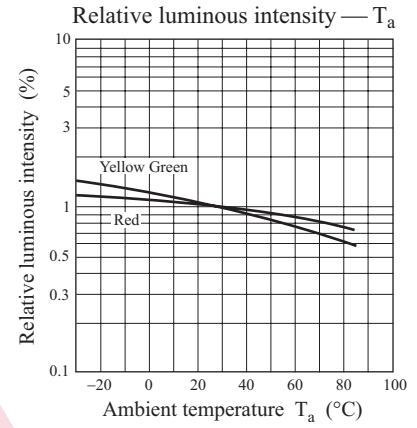
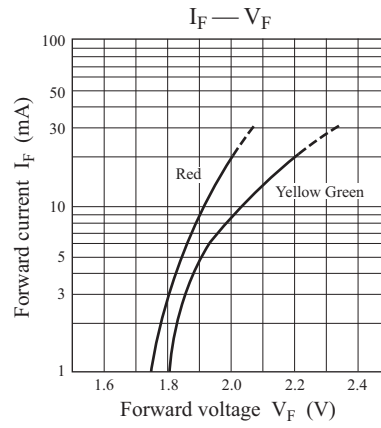
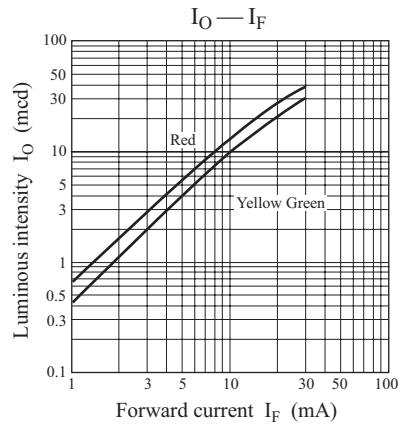
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

• Yellow Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 10\text{ mA}$	5.0	10		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm

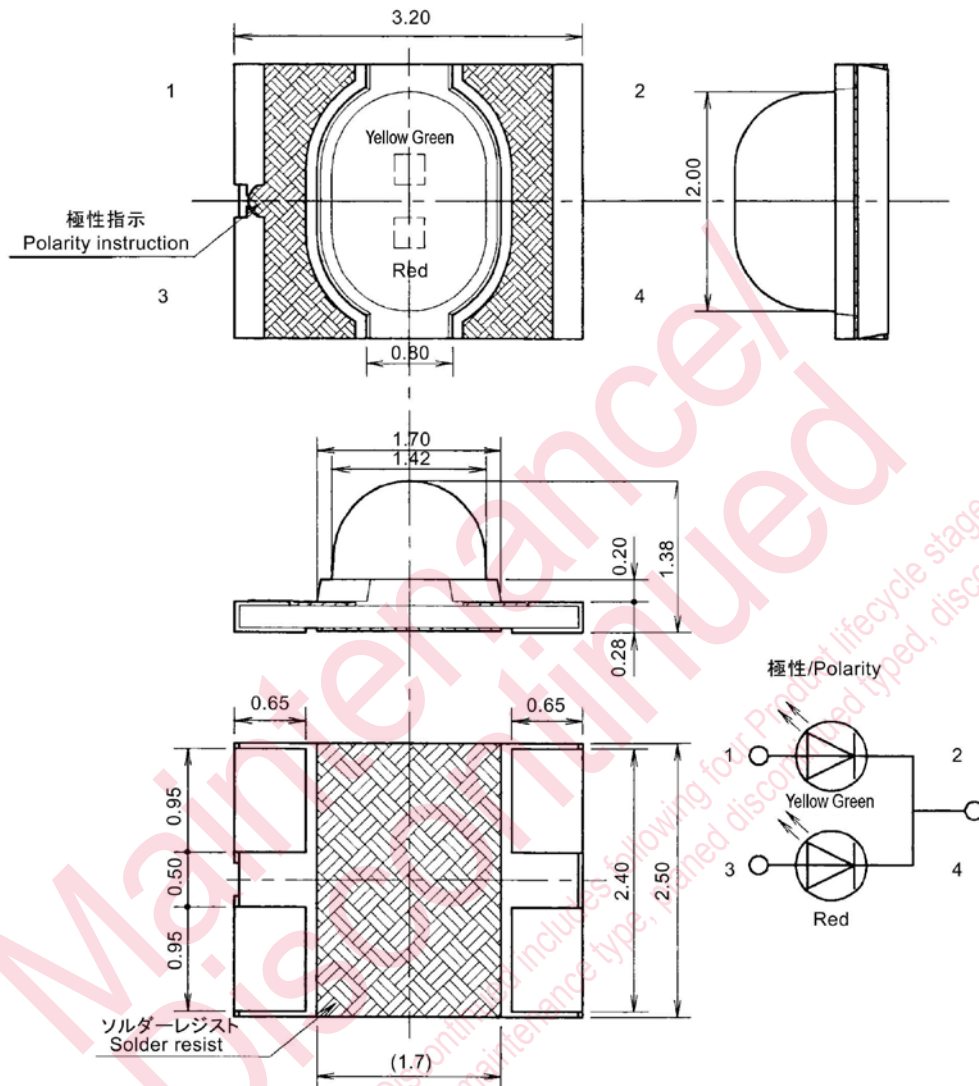
• Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 10\text{ mA}$	7.0	13.4		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.92	2.5	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		645		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		22		nm



■ Package (Unit: mm)

KLTLTN3K2130



• Pin name

- 1, 3: Anode
- 2, 4: Cathode

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